# **K30 Family Product Brief**

Supports all K30 devices



### 1 Kinetis Portfolio

Kinetis is the most scalable portfolio of low power, mixed-signal ARM<sup>®</sup>Cortex<sup>TM</sup>-M4 MCUs in the industry. Phase 1 of the portfolio consists of five MCU families with over 200 pin-, peripheral- and software-compatible devices. Each family offers excellent performance, memory and feature scalability with common peripherals, memory maps, and packages providing easy migration both within and between families.

Kinetis MCUs are built from Freescale's innovative 90nm Thin Film Storage (TFS) flash technology with unique FlexMemory (configurable embedded EEPROM). Kinetis MCU families combine the latest low-power innovations and high performance, high precision mixed-signal capability with a broad range of connectivity, human-machine interface, and safety & security peripherals. Kinetis MCUs are supported by a market-leading enablement bundle from Freescale and numerous ARM 3rd party ecosystem partners.

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#### **Kinetis Portfolio**

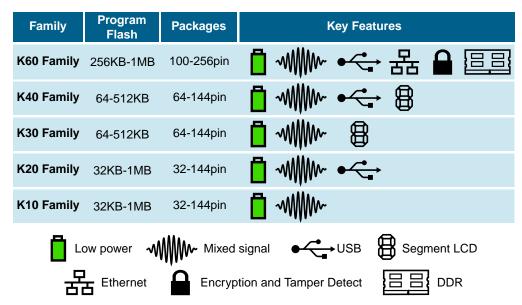


Figure 1. Kinetis MCU portfolio

All Kinetis families include a powerful array of analog, communication and timing and control peripherals with the level of feature integration increasing with flash memory size and the number of inputs/outputs. Features common to all Kinetis families include:

#### · Core:

- ARM Cortex-M4 Core delivering 1.25DMIPS/MHz with DSP instructions (floating-point unit available on certain Kinetis families)
- Up to 32-channel DMA for peripheral and memory servicing with minimal CPU intervention
- Broad range of performance levels rated at maximum CPU frequencies of 50 MHz, 72 MHz, and 100 MHz (120 MHz, 150 MHz, and 180 MHz available on certain Kinetis families)

#### • Ultra-low power:

- 10 low power operating modes for optimizing peripheral activity and wake-up times for extended battery life.
- · Low-leakage wake-up unit, low power timer, and low power RTC for additional low power flexibility

#### • Memory:

- Scalable memory footprints from 32 KB Flash / 8 KB RAM to 1 MB Flash / 128 KB RAM. Independent Flash banks enable concurrent code execution and firmware updates
- · Optional 16 KB cache memory for optimizing bus bandwidth and flash execution performance
- FlexMemory with up to 512 KB FlexNVM and up to 16 KB FlexRAM. FlexMemory can be partitioned for data flash memory, EEPROM, or traditional RAM

#### • Mixed-signal analog:

- Fast, high precision 16-bit ADCs, 12-bit DACs, programmable gain amplifiers, high speed comparators and an
  internal voltage reference. Powerful signal conditioning, conversion and analysis capability with reduced system
  cost
- Human Machine Interface (HMI):
  - · Capacitive Touch Sensing Interface with full low power support and minimal current adder when enabled
- Connectivity and Communications:
  - UARTs with ISO7816 and IrDA support, I2S, CAN, I2C and DSPI
- Reliability, Safety and Security:
  - Hardware cyclic redundancy check engine for validating memory contents / communication data and increased system reliability

- Independent-clocked COP for protection against code runaway in fail-safe applications
- · External watchdog monitor
- Timing and Control:
  - Powerful FlexTimers which support general purpose, PWM, and motor control functions
  - Carrier Modulator Transmitter for IR waveform generation
  - Programmable Interrupt Timer for RTOS task scheduler time base or trigger source for ADC conversion and programmable delay block
- External Interfaces:
  - Multi-function external bus interface capable of interfacing to external memories, gate-array logic, or an LCD
- System:
  - 5 V tolerant GPIO with pin interrupt functionality
  - Wide operating voltage range from 1.71 V to 3.6 V with flash programmable down to 1.71 V with fully functional flash and analog peripherals
  - Ambient operating temperature ranges from -40 °C to 105 °C

In addition to these common features, incremental capability is added to the specific Kinetis families as outlined in the following figure.

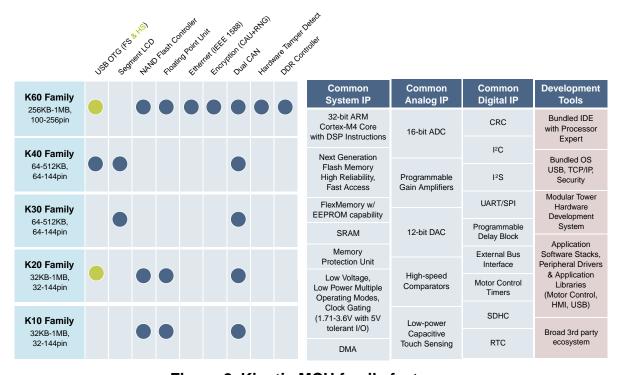


Figure 2. Kinetis MCU family features

# 2 K30 Family Introduction

The K30 MCU family is pin, peripheral and software compatible with the K10 MCU family and adds a flexible low-power segment LCD controller with support for up to 320 segments. Devices start from 64 KB of flash in 64QFN packages extending up to 512 KB in a 144MAPBGA package with a rich suite of analog, communication, timing and control peripherals.

# 3 K30 Block Diagram

The below figure shows a superset block diagram of the K30 device. Other devices within the family have a subset of the features.

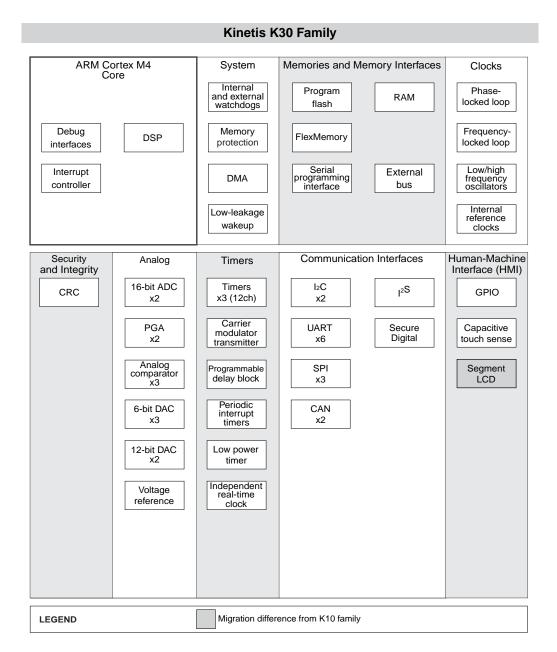


Figure 3. K30 Block Diagram

## 4 Features

# 4.1 Common features among the K30 family

All devices within the K30 family features the following at a minimum:

# Table 1. Common features among all K30 devices

Operating characteristics	• Voltago rango 1.71V 2.6V
Operating characteristics	<ul> <li>Voltage range 1.71V - 3.6V</li> <li>Flash memory programming down to 1.71V</li> </ul>
	Temperature range (T <sub>A</sub> ) -40 to 105°C
	Flexible modes of operation
Core features	Next generation 32-bit ARM Cortex-M4 core
	Supports DSP instructions     Newtonian distance to a stanting (ANVIC)
	Nested vectored interrupt controller (NVIC)     Asymptopage walks up interrupt controller (AVIC)
	<ul> <li>Asynchronous wake-up interrupt controller (AWIC)</li> <li>Debug &amp; trace capability</li> </ul>
	2-pin serial wire debug (SWD)
	IEEE 1149.1 Joint Test Action Group (JTAG)
	IEEE 1149.7 compact JTAG (cJTAG)
	Trace port interface unit (TPIU)
	<ul> <li>Flash patch and breakpoint (FPB)</li> </ul>
	Data watchpoint and trace (DWT)
	Instrumentation trace macrocell (ITM)
System and power manage-	<ul> <li>Software and hardware watchdog with external monitor pin</li> </ul>
ment	DMA controller with 16 channels
	Low-leakage wake-up unit (LLWU)     Dever management controller with 10 different power mades
	<ul> <li>Power management controller with 10 different power modes</li> <li>Non-maskable interrupt (NMI)</li> </ul>
	128-bit unique identification (ID) number per chip
Clocks	Multi-purpose clock generator
	<ul> <li>PLL and FLL operation</li> </ul>
	<ul> <li>Internal reference clocks (32kHz or 2MHz)</li> </ul>
	12MHz to 32MHz crystal oscillator
	32kHz to 40kHz crystal oscillator
	Internal 1kHz low power oscillator      DO to 50MHz systemal armore ways input alask.
	DC to 50MHz external square wave input clock
Memories and Memory In-	FlexMemory consisting of FlexNVM (non-volatile flash memory that can execute program
terfaces	code, store data, or backup EEPROM data) or FlexRAM (RAM memory that can be used
	as traditional RAM or as high-endurance EEPROM storage, and also accelerates flash pro-
	gramming)
	<ul> <li>Flash security and protection features</li> <li>Serial flash programming interface (EzPort)</li> </ul>
	- Genainash programming interface (EZF ort)
Security and integrity	Cyclic redundancy check (CRC)
Analog	16-bit SAR ADC
- 3	Programmable voltage reference (VREF)
	High-speed Analog comparator (CMP) with 6-bit DAC
Timers	1x8ch motor control/general purpose/PWM flexible timer (FTM)
	1x2ch quadrature decoder/general purpose/PWM flexible timer (FTM)
	Carrier modulator timer (CMT)
	Programmable delay block (PDB)

Communications	SPI I <sup>2</sup> C with SMBUS support UART (w/ ISO7816, IrDA and hardware flow control)
Human-machine interface	<ul> <li>GPIO with pin interrupt support, DMA request capability, digital glitch filter, and other pin control options</li> <li>5V tolerant inputs</li> <li>Capacitive touch sensing inputs</li> <li>LCD display driver         <ul> <li>Supports 3V or 5V glass</li> <li>Configurable frontplane and backplane pins</li> <li>Segment failure detection mechanism</li> </ul> </li> </ul>

# 4.1.1 Memory and package options for the K30 family

The following table summarizes the memory and package options for the K30 family. All devices which share a common package are pin-for-pin compatible.

**Table 2. K30 Family Summary** 

		Mer	nory		Package										
Perf. (MHz)	Flash (KB)	Flex NVM (KB)	SRAM (KB)	Flex RAM (KB)	32 QFN (5x5)	48 QFN (7x7)	48 LQFP (7x7)	64 QFN (9x9)	64 LQFP (10x10)	80 LQFP (12x12)	81 BGA (10x10)	100 LQFP (14x14)	104 BGA (10x10)	144 LQFP (20x20)	144 BGA (13x13)
50	64	32	16	2		_		+	+	+	+	_			_
50	128	32	32	2	_	_	_	+	+	+	+	+	+	_	_
72	128	32	32	2		_		+	+	+	+	+	+		_
72	256	32	64	2	_	_	_	_	_	+	+	+	+	_	_
100	128	128	32	4	_	_	_	_	_	_	_	_	_	+	+
100	256	256	64	4	_	_	_	_	_	_	_	_	_	+	+
100	512	_	128	_	_	_	_	_	_	+	+	+	+	+	+

# 4.2 Part Numbers and Packaging

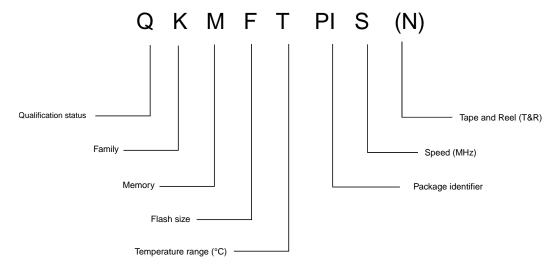


Figure 4. Part numbers diagrams

Field	Description	Values
Q	Qualification status	<ul> <li>M = Fully qualified, general market flow</li> <li>P = Product engineering</li> </ul>
K	Family	K30
М	Memory	<ul><li>N = Non-FlexMemory</li><li>X = FlexMemory</li></ul>
F	Flash size	• 16 = 16 KB • 32 = 32 KB • 64 = 64 KB • 128 = 128 KB • 256 = 256 KB • 512 = 512 KB • 1M0 = 1 MB •
Т	Temperature range (°C)	• V = -40 to 105

Field	Description	Values
PI	Package identifier	<ul> <li>FM = 32QFN</li> <li>FT = 48QFN</li> <li>LF = 48LQFP</li> <li>FX = 64QFN</li> <li>LH = 64LQFP</li> <li>LK = 80LQFP</li> <li>CB = 81MAPBGA</li> <li>LL = 100LQFP</li> <li>ML = 104MAPBGA</li> <li>LQ = 144LQFP</li> <li>MD = 144MAPBGA</li> <li>MF = 196MAPBGA</li> <li>MF = 256MAPBGA</li> </ul>
S	Speed (MHz)	<ul> <li>50 = 50 MHz</li> <li>72 = 72 MHz</li> <li>100 = 100 MHz</li> <li>120 = 120 MHz</li> <li>150 = 150 MHz</li> <li>180 = 180 MHz</li> </ul>
N	Tape and Reel (T&R)	<ul><li>Blank = Non T&amp;R</li><li>R = T&amp;R</li></ul>

# 4.3 K30 family features

The following sections list the differences among the various devices available within the K30 family. The sections are split by levels of performance.

# 4.3.1 K30 family features (50MHz Performance)

Table 3. K30 50MHz Performance Table

Partnumber	MK30X64VLH50(R)	MK30X128VLH50(R)	MK30X64VFX50(R)	MK30X128VFX50(R)	MK30X64VLK50(R)	MK30X128VLK50(R)	MK30X64VCB50(R)	MK30X128VCB50(R)	MK30X128VLL50(R)	MK30X128VML50(R)			
	General												
CPU Frequency	50MHz	50MHz	50MHz	50MHz	50MHz	50MHz	50MHz	50MHz	50MHz	50MHz			
Pin Count	64	64	64	64	80	80	81	81	100	104			
Package	LQFP	LQFP	QFN	QFN	LQFP	LQFP	MAP- BGA	MAP- BGA	LQFP	MAP- BGA			
	Memories and Memory Interfaces												
Total Flash Memory	96KB	160KB	96KB	160KB	96KB	160KB	96KB	160KB	160KB	160KB			
Flash	64KB	128KB	64KB	128KB	64KB	128KB	64KB	128KB	128KB	128KB			

Partnumber	MK30X64VLH50(R)	MK30X128VLH50(R)	MK30X64VFX50(R)	MK30X128VFX50(R)	MK30X64VLK50(R)	MK30X128VLK50(R)	MK30X64VCB50(R)	MK30X128VCB50(R)	MK30X128VLL50(R)	MK30X128VML50(R)
FlexNVM	32KB									
EEPROM/FlexRAM	2KB									
SRAM	16KB	32KB	16KB	32KB	16KB	32KB	16KB	32KB	32KB	32KB
External Bus Interface (Flexbus)	-	-	-	-	-	-	-	-	-	-
DDR Controller	-	-	-	-	-	-	-	-	-	-
NAND Flash Controller	-	-	-	-	-	-	-	-	-	-
Cache	-	-	-	-	-	-	-	-	-	-
			Core	e Module	s					
DSP	YES									
SPFPU	-	-	-	-	-	-	-	-	-	-
Debug	JTAG, cJTAG, SWD									
Trace	TPIU, FPB, DWT, ITM									
NMI	YES									
	'		Syste	m Modul	es			l .		
Software Watchdog	YES									
Hardware Watchdog	YES									
PMC	YES									
MPU	-	-	-	-	-	-	-	-	-	-
DMA	16ch									
			Cloc	k Module	s					
MCG	YES									
Main OSC (4-32MHz)	YES									
RTC (32KHz Osc, Vbat)	YES									
	•		Security	and Inte	grity					
Hardware Encryption	-	-	-	-	-	-	-	-	-	-
Tamper Detect	-	-	-	-	-	-	-	-	-	-
CRC	YES									
				Analog						

Γ	1	1	1							
Partnumber	MK30X64VLH50(R)	MK30X128VLH50(R)	MK30X64VFX50(R)	MK30X128VFX50(R)	MK30X64VLK50(R)	MK30X128VLK50(R)	MK30X64VCB50(R)	MK30X128VCB50(R)	MK30X128VLL50(R)	MK30X128VML50(R)
ADC0	14chSE	14chSE	14chSE	14chSE	14chSE	14chSE	14chSE	14chSE	16chSE	16chSE
	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 3chDP	+ 3chDP
ADC1	4chSE	4chSE	4chSE	4chSE	13chSE	13chSE	13chSE	13chSE	14chSE	14chSE
	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 3chDP	+ 3chDP
ADC2	-	-	-	-	-	-	-	-	-	-
ADC3	-	_	-	-	-	_	-	-	-	-
PGA	-	2	-	2	2	2	2	2	2	2
12-bit DAC	-	1	-	1	1	1	1	1	1	1
Analog Comparator	2	3	2	3	3	3	3	3	3	3
Vref	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES
	l	l	•	Timers						
Motor Control/General pur- pose/PWM	1x8ch	1x8ch	1x8ch	1x8ch	1x8ch	1x8ch	1x8ch	1x8ch	1x8ch	1x8ch
Quad decoder/General pur- pose/PWM	1x2ch	2x2ch	1x2ch	2x2ch	2x2ch	2x2ch	2x2ch	2x2ch	2x2ch	2x2ch
IEEE1588 Timer/General purpose/PWM	-	-	-	-	-	-	-	-	-	-
Low Power Timer	1	1	1	1	1	1	1	1	1	1
PIT	1x4ch	1x4ch	1x4ch	1x4ch	1x4ch	1x4ch	1x4ch	1x4ch	1x4ch	1x4ch
PDB	1	1	1	1	1	1	1	1	1	1
		С	ommunic	cation Int	erfaces					
Enhanced SDHC	-	-	-	-	-	-	-	-	-	-
Enhanced UART	1	1	1	1	1	1	1	1	1	1
UART	2	2	2	2	3	3	3	3	4	4
SPI	1	1	1	1	2	2	2	2	2	2
I2C	2	2	2	2	2	2	2	2	2	2
I2S	Play	Play	Play	Play	1	1	1	1	1	1
CAN	-	1	-	1	1	1	1	1	1	1
USB OTG LS/FS	-	-	-	-	-	-	-	-	-	-
USB OTG HS	-	-	-	-	-	-	-	-	-	-
USB DCD	-	-	-	-	-	-	-	-	-	-
USB 120mAReg	-	-	-	-	-	-	-	-	-	-
Ethernet w /1588	-	-	-	-	-	-	-	-	-	-

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Partnumber	MK30X64VLH50(R)	MK30X128VLH50(R)	MK30X64VFX50(R)	MK30X128VFX50(R)	MK30X64VLK50(R)	MK30X128VLK50(R)	MK30X64VCB50(R)	MK30X128VCB50(R)	MK30X128VLL50(R)	MK30X128VML50(R)
		H	luman-M	achine In	terface					
Segment LCD	16x8/20x4	16x8/20x4	16x8/20x4	16x8/20x4	24x8/28x4	24x8/28x4	25x8/29x4	25x8/29x4	32x8/36x4	36x8/40x4
CMT(Carrier Module Transmitter)	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES
TSI(Capacitive Touch)	16 input	16 input	16 input	16 input						
GPIO (w interrupt)	40	40	40	40	56	56	57	57	66	70
		C	perating	Characte	eristics	•				
5V Tolerant	YES	YES	YES	YES	YES	YES	YES	YES	YES	YES
Voltage Range	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V	1.71- 3.6V
Flash Write V	1.71V	1.71V	1.71V	1.71V	1.71V	1.71V	1.71V	1.71V	1.71V	1.71V
Temp Range	-40 to 105C	-40 to 105C	-40 to 105C	-40 to 105C						

# 4.3.2 K30 family features (72MHz Performance)

#### **Table 4. K30 72MHz Performance Table**

Partnumber	MK30X128VLH72(R)	MK30X128VFX72(R)	MK30X128VLK72(R)	MK30X256VLK72(R)	MK30X128VCB72(R)	MK30X256VCB72(R)	MK30X128VLL72(R)	MK30X256VLL72(R)	MK30X128VML72(R)	MK30X256VML72(R)		
General												
CPU Frequency	72MHz											
Pin Count	64	64	80	80	81	81	100	100	104	104		
Package	LQFP	QFN	LQFP	LQFP	MAP- BGA	MAP- BGA	LQFP	LQFP	MAP- BGA	MAP- BGA		
	•	Mem	ories and	Memory	Interfac	es						
Total Flash Memory	160KB	160KB	160KB	288KB	160KB	288KB	160KB	288KB	160KB	288KB		
Flash	128KB	128KB	128KB	256KB	128KB	256KB	128KB	256KB	128KB	256KB		
FlexNVM	32KB											
EEPROM/FlexRAM	2KB											
SRAM	32KB	32KB	32KB	64KB	32KB	64KB	32KB	64KB	32KB	64KB		

Partnumber	MK30X128VLH72(R)	MK30X128VFX72(R)	MK30X128VLK72(R)	MK30X256VLK72(R)	MK30X128VCB72(R)	MK30X256VCB72(R)	MK30X128VLL72(R)	MK30X256VLL72(R)	MK30X128VML72(R)	MK30X256VML72(R)
External Bus Interface (Flexbus)	-	-	•	•	-	-	-	•	-	-
DDR Controller	-	-	•	•	-	-	-	•	-	-
NAND Flash Controller	-	-	-	•	-	-	-	-	-	-
Cache	-	•	•	•	•	•	•	•	-	-
			Core	e Module	s					
DSP	YES									
SPFPU	-	-	-	-	-	-	-	-	-	-
Debug	JTAG, cJTAG, SWD									
Trace	TPIU, FPB, DWT, ITM									
NMI	YES									
			Syste	m Modul	es					
Software Watchdog	YES									
Hardware Watchdog	YES									
PMC	YES									
MPU	-	-	-	-	-	-	-	-	-	-
DMA	16ch									
			Cloc	k Module	S					
MCG	YES									
Main OSC (4-32MHz)	YES									
RTC (32KHz Osc, Vbat)	YES									
			Security	and Inte	grity					
Hardware Encryption	-	-	-	-	-	-	-	-	-	-
Tamper Detect	-	-	-	-	-	-	-	-	-	-
CRC	YES									
			-	Analog						
ADC0	14chSE +	14chSE +	14chSE +	14chSE +	14chSE +	14chSE +	16chSE +	16chSE +	16chSE +	16chSE +
	2chDP	2chDP	2chDP	2chDP	2chDP	2chDP	3chDP	3chDP	3chDP	3chDP

			1				· ·			
Partnumber	MK30X128VLH72(R)	MK30X128VFX72(R)	MK30X128VLK72(R)	MK30X256VLK72(R)	MK30X128VCB72(R)	MK30X256VCB72(R)	MK30X128VLL72(R)	MK30X256VLL72(R)	MK30X128VML72(R)	MK30X256VML72(R)
ADC1	4chSE	4chSE	13chSE	13chSE	13chSE	13chSE	14chSE	14chSE	14chSE	14chSE
	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 2chDP	+ 3chDP	+ 3chDP	+ 3chDP	+ 3chDP
ADC2	-	-	-	-	-	-	-	-	-	-
ADC3	-	-	-	-	-	-	-	-	-	-
PGA	2	2	2	2	2	2	2	2	2	2
12-bit DAC	1	1	1	1	1	1	1	1	1	1
Analog Comparator	3	3	3	3	3	3	3	3	3	3
Vref	YES									
			•	Timers						
Motor Control/General pur- pose/PWM	1x8ch									
Quad decoder/General pur- pose/PWM	2x2ch									
IEEE1588 Timer/General pur- pose/PWM	-	-	-	-	-	-	-	•	-	-
Low Power Timer	1	1	1	1	1	1	1	1	1	1
PIT	1x4ch									
PDB	1	1	1	1	1	1	1	1	1	1
		С	ommunio	cation Int	erfaces					
Enhanced SDHC	-	-	-	1	-	•	1	1	-	-
Enhanced UART	1	1	1	1	1	1	1	1	1	1
UART	2	2	3	3	3	3	4	4	4	4
SPI	1	1	2	2	2	2	2	2	2	2
I2C	2	2	2	2	2	2	2	2	2	2
I2S	Play	Play	1	1	1	1	1	1	1	1
CAN	1	1	1	1	1	1	1	1	1	1
USB OTG LS/FS	-	-	-	-	-	-	-	-	-	-
USB OTG HS	-	-	-	-	-	-	-	-	-	-
USB DCD	-	-	-	-	-	-	-	-	-	-
USB 120mAReg	-	-	-	-	-	-	-	-	-	-
Ethernet w /1588	-	-	-	-	-	-	-	-	-	-
		H	luman-M	achine In	terface					
Segment LCD	16x8/20x4	16x8/20x4	24x8/28x4	24x8/28x4	25x8/29x4	25x8/29x4	32x8/36x4	32x8/36x4	36x8/40x4	36x8/40x4

Partnumber	MK30X128VLH72(R)	MK30X128VFX72(R)	MK30X128VLK72(R)	MK30X256VLK72(R)	MK30X128VCB72(R)	MK30X256VCB72(R)	MK30X128VLL72(R)	MK30X256VLL72(R)	MK30X128VML72(R)	MK30X256VML72(R)
CMT(Carrier Module Transmitter)	YES									
TSI(Capacitive Touch)	16 input									
GPIO (w interrupt)	40	40	56	56	57	57	66	66	70	70
		C	perating	Characte	eristics					
5V Tolerant	YES									
Voltage Range	1.71- 3.6V									
Flash Write V	1.71V									
Temp Range	-40 to 105C									

# 4.3.3 K30 family features (100MHz Performance)

#### Table 5. K30 100MHz Performance Table

Partnumber	MK30X128VLQ100(R)	MK30X128VMD100(R)	MK30X256VLQ100(R)	MK30X256VMD100(R)	MK30N512VLK100(R)	MK30N512VCB100(R)	MK30N512VLL100(R)	MK30N512VML100(R)	MK30N512VLQ100(R)	MK30N512VMD100(R)
			0	Seneral						
CPU Frequency	100MHz									
Pin Count	144	144	144	144	80	81	100	104	144	144
Package	LQFP	MAP- BGA								
		Mem	ories and	Memory	Interface	es				
Total Flash Memory	256KB	256KB	512KB							
Flash	128KB	128KB	256KB	256KB	512KB	512KB	512KB	512KB	512KB	512KB
FlexNVM	128KB	128KB	256KB	256KB	-	-	-	-	-	-
EEPROM/FlexRAM	4KB	4KB	4KB	4KB	-	-	-	-	-	-
SRAM	32KB	32KB	64KB	64KB	128KB	128KB	128KB	128KB	128KB	128KB
External Bus Interface (Flexbus)	YES	YES	YES	YES	-	-	-	-	YES	YES

Partnumber	MK30X128VLQ100(R)	MK30X128VMD100(R)	MK30X256VLQ100(R)	MK30X256VMD100(R)	MK30N512VLK100(R)	MK30N512VCB100(R)	MK30N512VLL100(R)	MK30N512VML100(R)	MK30N512VLQ100(R)	MK30N512VMD100(R)
DDR Controller	-	-	-	-	-	-	-	-	-	-
NAND Flash Controller	-	-	-	-	-	-	-	-	-	-
Cache	-	-	-	-	-	-	-	-	-	-
				e Module						
DSP	YES									
SPFPU	-	-	-	-	-	-	-	-	-	-
Debug	JTAG, cJTAG, SWD									
Trace	TPIU, FPB, DWT, ITM, ETM, ETB									
NMI	YES									
			Syste	m Modul	es			•		
Software Watchdog	YES									
Hardware Watchdog	YES									
PMC	YES									
MPU	YES									
DMA	16ch									
			Cloc	k Module	S					
MCG	YES									
Main OSC (4-32MHz)	YES									
RTC (32KHz Osc, Vbat)	YES									
Security and Integrity										
Hardware Encryption	-	-	-	-	-	-	-	-	-	-
Tamper Detect	-	-	-	-	-	-	-	-	-	-
CRC	YES									
	1		•	Analog		1				
ADC0	19chSE +	19chSE +	19chSE +	19chSE +	14chSE +	14chSE +	16chSE +	16chSE +	19chSE +	19chSE +
	3chDP	3chDP	3chDP	3chDP	2chDP	2chDP	3chDP	3chDP	3chDP	3chDP

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Partnumber	MK30X128VLQ100(R)	MK30X128VMD100(R)	MK30X256VLQ100(R)	MK30X256VMD100(R)	MK30N512VLK100(R)	MK30N512VCB100(R)	MK30N512VLL100(R)	MK30N512VML100(R)	MK30N512VLQ100(R)	MK30N512VMD100(R)
ADC1	18chSE	18chSE	18chSE +	18chSE	13chSE	13chSE	14chSE	14chSE	18chSE	18chSE
	+ 3chDP	+ 3chDP	3chDP	+ 3chDP	+ 2chDP	+ 2chDP	+ 3chDP	+ 3chDP	+ 3chDP	+ 3chDP
ADC2	-	-	-	-	-	-	-	-	-	-
ADC3	-	-	-	-	-	-	-	-	-	-
PGA	2	2	2	2	2	2	2	2	2	2
12-bit DAC	2	2	2	2	1	1	1	1	2	2
Analog Comparator	3	3	3	3	3	3	3	3	3	3
Vref	YES									
			•	Timers						
Motor Control/General pur- pose/PWM	1x8ch									
Quad decoder/General pur- pose/PWM	2x2ch									
IEEE1588 Timer/General purpose/PWM	-	-	-	-	-	-	-	-	-	-
Low Power Timer	1	1	1	1	1	1	1	1	1	1
PIT	1x4ch									
PDB	1	1	1	1	1	1	1	1	1	1
		C	ommunio	cation Int	erfaces				,	
Enhanced SDHC	1	1	1	1	1	1	1	1	1	1
Enhanced UART	1	1	1	1	1	1	1	1	1	1
UART	5	5	5	5	3	3	4	4	5	5
SPI	3	3	3	3	2	2	3	3	3	3
I2C	2	2	2	2	2	2	2	2	2	2
I2S	1	1	1	1	1	1	1	1	1	1
CAN	2	2	2	2	1	1	2	2	2	2
USB OTG LS/FS	-	-	-	-	-	-	-	-	-	-
USB OTG HS	-	-	-	-	-	-	-	-	-	-
USB DCD	-	-	-	-	-	-	-	-	-	-
USB 120mAReg	-	-	-	-	-	-	-	-	-	-
Ethernet w /1588	-	-	-	-	-	-	-	-	-	-
		ŀ	luman-M	achine In	terface					
Segment LCD	40x8/44x4	40x8/44x4	40x8/44x4	40x8/44x4	24x8/28x4	25x8/29x4	32x8/36x4	36x8/40x4	40x8/44x4	40x8/44x4

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Partnumber	MK30X128VLQ100(R)	MK30X128VMD100(R)	MK30X256VLQ100(R)	MK30X256VMD100(R)	MK30N512VLK100(R)	MK30N512VCB100(R)	MK30N512VLL100(R)	MK30N512VML100(R)	MK30N512VLQ100(R)	MK30N512VMD100(R)
CMT(Carrier Module Transmitter)	YES									
TSI(Capacitive Touch)	16 input									
GPIO (w interrupt)	102	102	102	102	56	57	66	70	102	102
	•	C	perating	Charact	eristics					
5V Tolerant	YES									
Voltage Range	1.71- 3.6V									
Flash Write V	1.71V									
Temp Range	-40 to 105C									

## 4.4 Module-by-module feature list

The following sections describe the high-level module features for the family's superset device. See the previous section for differences among the subset devices.

### 4.4.1 Core modules

### 4.4.1.1 ARM Cortex-M4 Core

- Supports up to MHz frequency with 1.25DMIPS/MHz
- ARM Core based on the ARMv7 Architecture & Thumb<sup>®</sup>-2 ISA
- Microcontroller cores focused on very cost sensitive, deterministic, interrupt driven environments
- · Harvard bus architecture
- 3-stage pipeline with branch speculation
- Integrated bus matrix
- Integrated Digital Signal Processor (DSP)
- Configurable nested vectored interrupt controller (NVIC)
- Advanced configurable debug and trace components
- Embedded Trace Macrocell (ETM)

## 4.4.1.2 Nested Vectored Interrupt Controller (NVIC)

- Close coupling with Cortex-M4 core's Harvard architecture enables low latency interrupt handling
- Up to 120 interrupt sources
- Includes a single non-maskable interrupt
- 16 levels of priority, with each interrupt source dynamically configurable
- Supports nesting of interrupts when higher priority interrupts are activated
- Relocatable vector table

#### System modules

## 4.4.1.3 Wake-up Interrupt Controller (WIC)

- Supports interrupt handling when system clocking is disabled in low power modes
- Takes over and emulates the NVIC behavior when correctly primed by the NVIC on entry to very-deep-sleep
- A rudimentary interrupt masking system with no prioritization logic signals for wake-up as soon as a non-masked interrupt is detected
- Contains no programmer's model visible state and is therefore invisible to end users of the device other than through the benefits of reduced power consumption while sleeping

### 4.4.1.4 Debug Controller

- Serial Wire JTAG Debug Port (SWJ-DP) combines
  - external interface that provides a standard JTAG or cJTAG interface for debug access
  - · external interface that provides a serial-wire bidirectional debug interface
- Debug Watchpoint and Trace (DWT) with the following functionality:
  - four comparators configurable as a hardware watchpoint, an ETM trigger, a PC sampler event trigger, or a data address sampler event trigger
  - several counters or a data match event trigger for performance profiling
  - configurable to emit PC samples at defined intervals or to emit interrupt event information
- Instrumentation Trace Macrocell (ITM) with the following functionality:
  - Software trace writes directly to ITM stimulus registers can cause packets to be emitted
  - Hardware trace packets generated by DWT are emitted by ITM
  - Time stamping emitted relative to packets
- Embedded Trace Macrocell (ETM) supports instruction trace
- CoreSight<sup>™</sup> Embedded Trace Buffer (ETB) is a memory-mapped buffer to store trace data
- Test Port Interface Unit (TPIU) acts as a bridge between ITM or ETM and an off-chip Trace Port Analyzer
- Flash Patch and Breakpoints (FPB) implements hardware breakpoints and patches code and data from code space to system space

## 4.4.2 System modules

### 4.4.2.1 Power Management Control Unit (PMC)

- Separate digital (regulated) and analog (referenced to digital) supply outputs
- Programmable power saving modes
- No output supply decoupling capacitors required
- Available wake-up from power saving modes via RTC and external inputs
- Integrated Power-on Reset (POR)
- Integrated Low Voltage Detect (LVD) with reset (brownout) capability
- Selectable LVD trip points
- Programmable Low Voltage Warning (LVW) interrupt capability
- Buffered bandgap reference voltage output
- Factory programmed trim for bandgap and LVD
- 1 kHz Low Power Oscillator (LPO)

# 4.4.2.2 DMA Channel Multiplexer (DMA MUX)

- 16 independently selectable DMA channel routers
- 4 periodic trigger sources available
- Each channel router can be assigned to 1 of 64 possible peripheral DMA sources

#### 4.4.2.3 DMA Controller

- Up to 32 fully programmable channels with 32-byte transfer control descriptors
- Data movement via dual-address transfers for 8-, 16-, 32- and 128-bit data values
- · Programmable source, destination addresses, transfer size, support for enhanced address modes
- · Support for major and minor nested counters with one request and one interrupt per channel
- Support for channel-to-channel linking and scatter/gather for continuous transfers with fixed priority and round-robin channel arbitration

### 4.4.2.4 Watchdog Timer (WDOG)

- Independent, configurable clock source input
- Write-once control bits with unlock sequence
- · Programmable timeout period
- · Ability to test watchdog timer and reset
- · Windowed refresh option
- · Robust refresh mechanism
- · Cumulative count of watchdog resets between power-on resets
- Configurable interrupt on timeout

### 4.4.2.5 External Watchdog Monitor (EWM)

- Independent 1 kHz LPO clock source
- · Output signal to gate an external circuit which is controlled by CPU service or external input

### 4.4.2.6 System Clocks

- Frequency-locked loop (FLL)
  - Digitally-controlled oscillator (DCO)
  - DCO frequency range is programmable
  - Option to program DCO frequency for a 32,768 Hz external reference clock source
  - Internal or external reference clock can be used to control the FLL
  - 0.2% resolution using 32 kHz internal reference clock
  - 2% deviation over voltage and temperature using internal 32 kHz internal reference clock, 1% deviation with limited temperature range (0°C to 70°C)
- Phase-locked loop (PLL)
  - Voltage-controlled oscillator (VCO)
  - External reference clock is used to control the PLL
  - Modulo VCO frequency divider Phase/Frequency detector
  - Integrated loop filter
- Internal reference clock generator
  - · Slow clock with nine trim bits for accuracy
  - Fast clock with four trim bits
  - Can be used to control the FLL
  - Either the slow or the fast clock can be selected as the clock source for the MCU
  - Can be used as a clock source for other on-chip peripherals
- External clock from the Crystal Oscillator (XOSC)
  - Can be used to control the FLL and/or the PLL
  - Can be selected as the clock source for the MCU
- External clock monitor with reset request capability
- Lock detector with interrupt request capability for use with the PLL
- Auto Trim Machine (ATM) for trimming both the slow and fast internal reference clocks
- Reference dividers for both the FLL and PLL are provided

#### **Memories and Memory Interfaces**

- Clock source selected can be divided down by 1, 2, 4, or 8
- MCGPLLSCLK is provided as a clock source from either the FLL or PLL for other on-chip peripherals
- MCGFFCLK is provided as a clock source for other on-chip peripherals

## 4.4.3 Memories and Memory Interfaces

## 4.4.3.1 On-Chip Memory

- 50MHz performance devices
  - Up to 128KB program flash memory
  - Flex memory block contains up to 32KB FlexNVM and 2KB FlexRAM with up to 2KB EEPROM capability
  - Up to 32KB SRAM
- 72MHz performance devices
  - Up to 256KB program flash memory
  - Flex memory block contains up to 32KB FlexNVM and 2KB FlexRAM with up to 2KB EEPROM capability
  - Up to 64KB SRAM
- 100MHz performance devices
  - Up to 512KB program flash memory
  - Flex memory block contains up to 256KB FlexNVM and 4KB FlexRAM with up to 4KB EEPROM capability
  - Up to 128KB SRAM
- Security circuitry to prevent unauthorized access to RAM and flash contents

### 4.4.3.2 External Bus Interface (FlexBus)

- Six independent, user-programmable chip-select signals that can interface with external SRAM, PROM, EPROM, EEPROM, flash, and other peripherals
- Supports up to 2 GB addressable space
- 8-, 16- and 32-bit port sizes with configuration for multiplexed or non-multiplexed address and data buses
- Byte-, word-, longword-, and 16-byte line-sized transfers
- Programmable address-setup time with respect to the assertion of chip select
- · Programmable address-hold time with respect to the negation of chip select and transfer direction

## 4.4.3.3 Serial Programming Interface (EzPort)

- · Same serial interface as, and subset of, the command set used by industry-standard SPI flash memories
- Ability to read, erase, and program flash memory
- Reset command to boot the system after flash programming

### 4.4.4 Security and Integrity

### 4.4.4.1 Cyclic Redundancy Check (CRC)

- Hardware CRC generator circuit using 16/32-bit shift register
- User Configurable 16/32 bit CRC
- Programmable Generator Polynomial
- Error detection for all single, double, odd, and most multi-bit errors
- Programmable initial seed value
- High-speed CRC calculation
- Optional feature to transpose input data and CRC result via transpose register, required on applications where bytes are
  in lsb format

## 4.4.5 Analog

### 4.4.5.1 16-bit Analog-to-Digital Converter (ADC)

- Linear successive approximation algorithm with up to 16-bit resolution
- Up to 14.5 ENOB
- Up to four pairs of differential and 24 single-ended external analog inputs
- Output modes:
  - Differential 16-bit, 13-bit, 11-bit, and 9-bit modes, in two's complement 16-bit sign-extended format
  - Single-ended 16-bit, 12-bit, 10-bit, and 8-bit modes, in right-justified unsigned format
- Single or continuous conversion
- Configurable sample time and conversion speed/power
- Conversion complete and hardware average complete flag and interrupt
- Input clock selectable from up to four sources
- Operation in low power modes for lower noise operation
- Asynchronous clock source for lower noise operation with option to output the clock
- Selectable asynchronous hardware conversion trigger with hardware channel select
- · Automatic compare with interrupt for various programmable values
- · Temperature sensor
- · Hardware average function
- Selectable voltage reference
- Self-calibration mode

### 4.4.5.2 High-Speed Analog Comparator (CMP)

- 6-bit DAC programmable reference generator output
- Typically 5 mV of input offset
- Less than 40 µA power consumption in enable mode and less than 1 nA in disable mode (excluding programmable reference generator)
- Fixed ACMP hysteresis from 3 mV to 20 mV
- Up to eight selectable comparator inputs; each input can be compared with any input by any polarity sequence
- · Selectable interrupt on rising edge, falling edge, or either rising or falling edges of comparator output
- · Comparator output may be sampled, windowed(ideal for zero cross detection) or digitilly filtered
- · Remains operational in low power mode

## 4.4.5.3 12-Bit Digital-to-Analog Converter (DAC)

- 12-bit resolution
- Guaranteed 6-sigma monotocity over input word 497–3599
- High- and low-speed conversions
  - 1 us conversion rate for high speed, 2 us for low speed
- Power-down mode
- DAC can drive 3-kOhm, 400-pF load
- Choice of asynchronous or synchronous updates
- Automatic mode allows the DAC to generate its own output waveforms including square, triangle, and sawtooth
- Automatic mode allows programmable period, update rate, and range
- DMA support with configurable watermark level

## 4.4.5.4 Voltage Reference (VREF)

- Programmable trim register with 0.5mV steps, automatically loaded with room temp value upon reset
- Programmable mode selection:
  - Off
  - Bandgap out (or stabilization delay)

#### **Timers**

- · Low-Power buffer mode
- Tight-Regulation buffer mode
- 1.2 V output at room temperature, 40 ppm/C
- Dedicated output pin, VREFO
- Load Regulation in tight-regulation mode of 100 uV/mA max
- PSR of 0.1 mV DC and -60dB AC

#### **4.4.6 Timers**

### 4.4.6.1 Programmable Delay Block (PDB)

- Up to 15 trigger input sources and software trigger source
- Up to eight configurable PDB channels for ADC hardware trigger
  - One PDB channel is associated with one ADC.
  - One trigger output for ADC hardware trigger and up to eight pre-trigger outputs for ADC trigger select per PDB channel
  - Trigger outputs can be enabled or disabled independently.
  - One 16-bit delay register per pre-trigger output
  - Optional bypass of the delay registers of the pre-trigger outputs
  - Operation in One-Shot or Continuous modes
  - Optional back-to-back mode operation, which enables the ADC conversions complete to trigger the next PDB channel
  - · One programmable delay interrupt
  - One sequence error interrupt
  - One channel flag and one sequence error flag per pre-trigger
  - DMA support
- Up to eight DAC interval triggers
  - One interval trigger output per DAC
  - One 16-bit delay interval register per DAC trigger output
  - Optional bypass the delay interval trigger registers
  - · Optional external triggers
- Up to eight pulse outputs (pulse-out's)
  - Pulse-out's can be enabled or disabled independently.
  - · Programmable pulse width

## 4.4.6.2 FlexTimers (FTM)

- · Selectale FTM source clock
- Programmable prescaler
- 16-bit counter supporting free-running or initial/final value, and countin is up or up-down
- Input capture, output compare, and edge-aligned and center-aligned PWM modes
- Input capture and output compare modes
- Operation of FTM channels as pairs with equal outputs, pairs with complimentary outputs, or independent channels with independent outputs
- Deadtime insertion is available for each complementary pair
- Generation of hardware triggers
- · Software control of PWM outputs
- Up to 4 fault inputs for global fault control
- · Configurable channel polarity
- · Programmable interrupt on input capture, reference compare, overflowed counter, or detected fault condition
- Quadrature decoder with input filters, relative position counting, and interrupt on position count or capture of position count on external event

- DMA support for FTM events
- Global time base mode shares single time base across multiple FTM instances

### 4.4.6.3 Programmable Interrupt Timers (PITs)

- Up to 4 general purpose interrupt timers
- Up to 4 interrupt timers for triggering ADC conversions
- 32-bit counter resolution
- · Clocked by system clock frequency
- DMA support

#### 4.4.6.4 Low Power Timer

- Selectable clock for prescaler/glitch filter
  - 1 kHz internal LPO
  - 32.768 kHz external crystal
  - Internal Reference Clock (not usable in low leakage modes)
- Configurable Glitch Filter or Prescaler with 15-bit counter
- 16-bit Time or Pulse Counter with Compare
- Interrupt generated on Timer Compare
- Hardware trigger generated on Timer Compare (not usable in low leakage modes)

### 4.4.6.5 Carrier Modulator Timer (CMT)

- Four modes of operation
  - Time; with independent control of high and low times
  - Baseband
  - Frequency shift key (FSK)
  - Direct software control of CMT\_IRO signal
- Extended space operation in time, baseband, and FSK modes
- · Selectable input clock divider
- Interrupt on end of cycle
  - Ability to disable CMT IRO signal and use as timer interrupt

## 4.4.6.6 Real-Time Clock (RTC)

- Independent power supply, POR and 32 kHz crystal oscillator
- 32-bit seconds counter with 32-bit Alarm
- 16-bit prescaler with compensation that can correct errors between 0.12 ppm and 3906 ppm
- · Register write protection
  - Hard Lock requires VBAT POR to enable write access
  - Soft lock requires system reset to enable write/read access

## 4.4.7 Communication interfaces

#### 4.4.7.1 CAN Module

- Supports the full implementation of the CAN Specification Version 2.0, Part B
  - Standard data and remote frames (up to 109 bits long)
  - Extended data and remote frames (up to 127 bits long)
  - 0-8 bytes data length
  - Programmable bit rate up to 1 Mbit/sec
  - · Content-related addressing

#### **Communication interfaces**

- Flexible message buffers (MBs), totalling up to 16 message buffers of 0–8 bytes data length each, configurable as Rx or Tx, all supporting standard and extended messages
- Listen-only mode capability
- Individual mask registers for each message buffer
- Programmable transmit-first scheme: lowest ID or lowest buffer number
- Timestamp based on 16-bit free-running timer
- Global network time, synchronized by a specific message

### 4.4.7.2 Serial Peripheral Interface (SPI)

- Full-duplex, three-wire synchronous transfers
- · Master and slave mode
- Buffered transmit operation using the TX FIFO with depth of up to 4 entries
- Buffered receive operation using the RX FIFO with depth of up to 4 entries
- TX and RX FIFOs can be disabled individually for low-latency updates to SPI queues
- Visibility into TX and RX FIFOs for ease of debugging
- Programmable transfer attributes on a per-frame basis
- Depending on which DSPI instance and package, up to 6 peripheral chip selects (expandable to 64 with external demultiplexer)
- Deglitching support for up to 32 peripheral chip selects with external demultiplexer
- DMA support for adding entries to the transmit FIFO and removing entries from the receive FIFO
- 6 interrupt conditions
- Modified SPI transfer formats for communication with slower peripheral devices

# 4.4.7.3 Inter-Integrated Circuit (I<sup>2</sup>C)

- Compatible with I<sup>2</sup>C bus standard and SMBus version 2 features
- Up to 100 kbps with maximum bus loading, 400kbps supported with limited bus loading
- Multi-master operation
- Software programmable for one of 64 different serial clock frequencies
- · Programmable slave address and glitch input filter
- Interrupt driven byte-by-byte data transfer
- Arbitration lost interrupt with automatic mode switching from master to slave
- Calling address identification interrupt
- Bus busy detection broadcast and 10-bit address extension
- Address matching causes wake-up when processor is in low power mode
- DMA support

#### 4.4.7.4 UART

- Full-duplex operation
- Standard mark/space non-return-to-zero (NRZ) format
- Selectable IrDA 1.4 return-to-zero-inverted (RZI) format with programmable pulse widths
- Support for ISO 7816 protocol for interfacing with smartcards
- 13-bit baud rate selection with fractional divide of 32
- Programmable 8-bit or 9-bit data format
- Separately enabled transmitter and receiver
- Programmable transmitter output polarity
- Programmable receive input polarity
- 13-bit break character option
- 11-bit break character detection option
- Two receiver wakeup methods:
  - · Idle line wakeup
  - · Address mark wakeup
- Address match feature in receiver to reduce address mark wakeup ISR overhead

- Interrupt-driven operation with 10 flags
- · Receiver framing error detection
- Hardware parity generation and checking
- 1/16 bit-time noise detection
- · DMA requests

### 4.4.7.5 Secure Digital Host Controller (SDHC)

- Compatible with the following specifications:
  - SD Host Controller Standard Specification, Version 2.0 (http://www.sdcard.org) with test event register and advanced DMA support
  - MultiMediaCard System Specification, Version 4.2 (http://www.mmca.org)
  - SD Memory Card Specification, Version 2.0 (http://www.sdcard.org), supporting high capacity SD memory cards
  - SDIO Card Specification, Version 2.0 (http://www.sdcard.org)
  - CE-ATA Card Specification, Version 1.0 (http://www.sdcard.org)
- Designed to work with CE-ATA, SD Memory, miniSD Memory, SDIO, miniSDIO, SD Combo, MMC, MMCplus, and RS-MMC cards
- SD bus clock frequency up to 50 MHz
- Supports 1-/4-bit SD and SDIO modes, 1-/4-/8-bit MMC modes, 1-/4-/8-bit CE-ATA devices
- Up to 200 Mbps data transfer for SD/SDIO cards using four parallel data lines
- Up to 416 Mbps data transfer for MMC using 8 parallel data lines
- Single- and multi-block read and write
- 1-4096 byte block size
- · Write-protection switch for write operations
- · Synchronous and asynchronous abort
- · Pause during the data transfer at a block gap
- SDIO read wait and suspend/resume operations
- Auto CMD12 for multi-block transfer
- Host can initiate non-data transfer commands while the data transfer is in progress
- Allows cards to interrupt the host in 1- and 4-bit SDIO modes
- Supports interrupt period, defined in the SDIO standard
- Fully configurable 128 x 32-bit FIFO for read/write data
- Internal DMA capabilities
- Supports voltage selection by configuring vendor specific register bit
- Supports advanced DMA to perform linked memory access

## 4.4.7.6 Synchronous Serial Interface (I2S)

- Independent (asynchronous) or shared (synchronous) transmit and receive sections with separate or shared internal/external clocks and frame syncs, operating in Master or Slave mode.
- Master or slave mode operation
- Normal mode operation using frame sync
- Network mode operation allowing multiple devices to share the port with up to 32 time slots
- Programmable data interface modes, such as I<sup>2</sup>S, LSB aligned, and MSB aligned
- Programmable word length (8, 10, 12, 16, 18, 20, 22 or 24 bits)
- AC97 support

#### 4.4.8 Human-machine interface

## 4.4.8.1 General Purpose Input/Output (GPIO)

- Progammable glitch filter and interrupt with selectable polarity on all input pins
- Hysteresis and configurable pull up/down device on all input pins
- Configurable slew rate and drive strength on all output pins

#### Power modes

- Independent pin value register to read logic level on digital pin
- Optional devices with 5V tolerance

#### 4.4.8.2 Touch Sensor Input (TSI)

- 16 channel inputs, supporting up to 16 individual touch buttons
- 4 touch buttons can be combined for a slider
- Configurable button- and slider-sensitive interrupts
- Operation in low-power modes
- Option to use internal reference clock

### 4.4.8.3 Segment LCD

- LCD waveforms functional in low-power modes
- Up to 48 LCD pins with selectable frontplane/backplane configuration
  - Generate up to 44 frontplane signals
  - Generate up to 8 backplanes signals
- Programmable LCD frame frequency
- Programmable blink modes and frequency
  - · All segments blank during blink period
  - Alternate display for each LCD segment in x4 or less mode
  - · Blink operation in low-power modes
- Programmable LCD power supply switch, making it an ideal solution for battery-powered and board-level applications
  - Charge pump requires only four external capacitors
  - Internal LCD power using VDD (1.8 to 3.6 V)
  - Internal VIREG regulated power supply option for 3 V or 5 V LCD glass
  - External VLL3 power supply option (3 V)
- Internal-regulated voltage source with a 4-bit trim register to apply contrast control
- Integrated charge pump for generating LCD bias voltages
  - Hardware-configurable to drive 3 V or 5 V LCD panels
  - On-chip generation of bias voltages
- Waveform storage registers
- Backplane reassignment to assist in vertical scrolling on dot-matrix displays
- Software-configurable LCD frame frequency interrupt

### 5 Power modes

The power management controller (PMC) provides the user with multiple power options. All together 10 different modes of operation are supported to allow the user to optimize power consumption for the level of functionality needed.

Depending on the stop requirements of the user application, a variety of stop modes are available that provide state retention, partial power down or full power down of certain logic and/or memory. I/O states are held in all modes of operation. The following table compares the various power modes available.

For each run mode there is a corresponding wait and stop mode. Wait modes are similar to ARM sleep modes. Stop modes (VLPS, STOP) are similar to ARM deep sleep mode. The very low power run (VLPR) operating mode can drastically reduce runtime power when the maximum bus frequency is not required to handle the application needs.

The CPU has three primary modes of operation: run, wait and stop. The WFI and WFE instruction are used to invoke both wait and stop modes for the chip. The chip augments stop, wait, and run in a number of ways to provide lower power based on application needs.

Table 6. Chip power modes

Power mode	Description	Normal recovery method
Normal run	Allows maximum performance of chip.	-
Normal Wait - via WFI	Allows peripherals to function, while allowing CPU to go to sleep reducing power.	Interrupt
Normal Stop - via WFI	Places chip in static state. Lowest power mode that retains all registers while maintaining LVD protection.	Interrupt
Normal Stop - via WFE	Places chip in static state. Lowest power mode that retains all registers while maintaining LVD protection.	Resume
VLPR (Very Low Power Run)	Reduced frequency (1MHz) Flash access mode, regulator in low power mode, LVD off, Internal oscillator provides low power 2 MHz source for core and peripherals.	Interrupt
VLPW (Very Low Power Wait) -via WFI	Similar to VLPR, with CPU in sleep to further reduce power.	Interrupt
VLPS (Very Low Power Stop)-via WFI	Places chip in static state, with LVD operation off. Lowest power mode with ADC and pin interrupts functional. LPTimer, RTC, ACMP, DAC can be used .	Interrupt
VLPS (Very Low Power Stop)-via WFE	Places chip in static state, with LVD operation off. Lowest power mode with ADC and pin interrupts functional. LPTimer, RTC, ACMP, DAC can be used .	Resume
LLS (Low Leakage Stop)	State retention power mode. LLWU, LPTimer, RTC, ACMP, DAC can be used.  NOTE: The LLWU interrupt must not be masked by the interrupt controller to avoid a scenario where the system does not fully exit stop mode on an LLS recovery.	Wakeup Interrupt
VLLS3 (Very Low Leakage Stop3)	LLWU, LPTimer, RTC, ACMP, DAC can be used. SRAM_U and SRAM_L remain powered on.	Wakeup Reset
VLLS2 (Very Low Leakage Stop2)	LLWU, LPTimer, RTC, ACMP, DAC can be used. SRAM_L is powered off. A portion of SRAM_U remains powered on.	Wakeup Reset
VLLS1 (Very Low Leakage Stop1)	LLWU, LPTimer, RTC, ACMP, DAC can be used. All of SRAM_U and SRAM_L are powered off. 32-byte VBAT register file for customer-critical data remains powered.	Wakeup Reset

# 6 Developer Environment

Freescale's products are supported by a widespread, established network of tools and third party developers and software vendors. The Kinetis families take advantage of these and similar development resources.

# 6.1 Freescale's Tower System Support

Freescale's Tower System is a modular development platform for 8-bit, 16-bit, and 32-bit microcontrollers that enables advanced development through rapid prototyping. Featuring multiple development boards or modules, the Tower System provides designers with building blocks for entry-level to advanced microcontroller development.

#### **Developer Environment**

#### The Freescale Tower System MCU/MPU Module **Primary Elevator** Common serial • Tower controller board and expansion bus signals Works stand-alone or in Tower System • Two 2x80 connectors on backside for easy · Features new on-board signal access and debug interface for side-mounting board easy programming (i.e. LCD module) and debugging via mini-B USB cable Power regulation circuitry Secondary Elevator Standardized signal assignments Additional serial and expansion buses and peripheral interfaces **Board Connectors** Four card-edge connectors Uses PCI Express ® connectors (x16, 90 mm/3.5" long, 164 pins) **Peripheral Module** • Tower is approx. 3.5" H x 3.5" W x 3.5" D • (i.e. serial, prototype, etc.) when fully assembled

Figure 5. Freescale's Tower System

The following Tower modules are available for the Kinetis families. For more information on the Tower System see <a href="http://www.freescale.com/tower">http://www.freescale.com/tower</a>.

**Table 7. Tower Modules for Kinetis MCU Families** 

Microcontroller Modules	Features
Kinetis K40 Family MCU Module	K40 family 512 KB flash MCU in 144 MAPBGA package
	On-board JTAG debug interface
	Access to all features including Segment LCD and USB
Kinetis K60 Family MCU Module	K60 family 512 KB flash MCU in 144 MAPBGA package
	On-board JTAG debug interface
	Access to all features including Ethernet and USB

# 6.2 CodeWarrior Development Studio

Freescale's CodeWarrior Development Studio for Microcontrollers v10.x integrates the development tools for the RS08, HCS08, ARM, and ColdFire architectures into a single product based on the Eclipse open development platform. Eclipse offers an excellent framework for building software development environments and is becoming a standard framework used by many embedded software vendors.

- Eclipse IDE 3.4
- Build system with optimizing C/C++ compilers for RS08, HCS08, ARM, and ColdFire processors
- Extensions to Eclipse C/C++ Development Tools (CDT) to provide sophisticated features to troubleshoot and repair embedded applications

Table 8. CodeWarrior 10.x Differentiating Features

Differentiating features	Customer benefits	Details
MCU Change Wizard	Ability to eas- ily retarget project to a new pro- cessor	Simply select a new device (from the same or a different architecture) and select the default connection, and the CodeWarrior tool suite automatically reconfigures the project for the new device with the correct build tools and support files.  • Compiler  • Assembler  • Linker  • Header files  • Vector tables  • Libraries  • Linker configuration files
Freescale Processor Expert	Problems in hardware lay- er can be re- solved during initial design phase	Combines easy-to-use component-based application creation with an expert knowledge system.  CPU, on-chip peripherals, external peripherals, and software functionality are encapsulated into embedded components  Each component's functionality can be tailored to fit application requirements by modifying the component's properties, methods and events  When the project is built, Processor Expert automatically generates highly optimized embedded C code and places the source files into the project  Graphical user interface: Allows an application to be specified by the functionality needed  Automatic code generator: Creates tested, optimized C code tuned to application needs and the selected Freescale device  Built-in knowledgebase: Immediately flags resource conflicts and incorrect settings, so errors are caught early in design cycle  Component wizard: Allows user-specific, hardware-independent embedded components to be created
Trace and profile support for on- chip trace buffers	Sophisticated emulator-like debug capab- ility without additional hardware	The CodeWarrior profiling and analysis tools provide visibility into an application as it runs on the processor to identify operational problems.  • Supports architectures with on-chip trace buffers (HCS08, V1 ColdFire, ARM)  • Allows tracepoints to be set to enable and disable trace output  • Can step through trace data and the corresponding source code simultaneously  • Allows trace data to be exported into a Microsoft® Excel® file

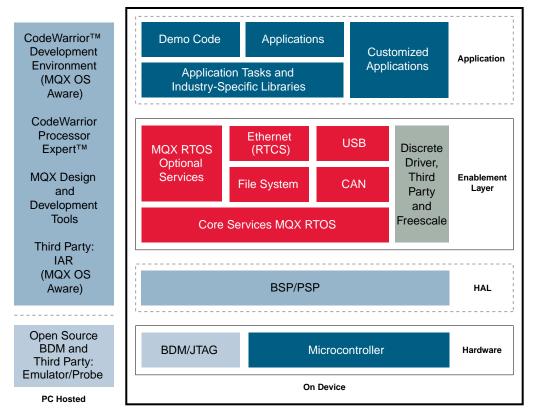
## 6.3 Freescale's MQX™ Software Solutions

The increasing complexity of industrial applications and expanding functionality of semiconductors are driving embedded developers toward solutions that combine proven hardware and software platforms. These solutions help accelerate time to market and improve application development success.

Freescale Semiconductor offers the MQX real-time operating system (RTOS), with TCP/IP and USB software stacks and peripheral drivers, to customers of ARM, ColdFire and ColdFire+ MCUs at no additional charge. The combination of Freescale's MQX software solutions and Freescale's silicon portfolio creates a comprehensive source for hardware, software, tools, and services.

#### **Developer Environment**

#### **Freescale Comprehensive Solution**



**Figure 6. MQX Comprehensive Solution** 

Key benefits of Freescale's MQX RTOS include:

- Small memory footprint: The RTOS was designed for speed and size efficiency in embedded systems. It delivers true real-time performance, with context switching and low-level interrupt routines hand-optimized in assembly.
- Component-based architecture: Provides a fully-functional RTOS core with additional, optional services. Freescale's MQX RTOS includes 25 components (8 core components and 17 optional). Components are linked in only if needed, preventing unused functions from bloating the memory footprint.
- Full and lightweight components: Key components are included in both full and lightweight versions for further control of size, RAM/ROM utilization, and performance options.
- Real-time, priority-based, preemptive multithreading: Allows high-priority threads to meet their deadlines consistently, no matter how many other threads are competing for CPU time.
- Scheduling: Enables faster development time by offloading from developers the task of creating or maintaining an efficient scheduling system and interrupt handling.
- Code reuse: Provides a framework with a simple, intuitive API to build and organize the features across Freescale's broad portfolio of embedded processors.
- Fast boot sequence: Ensures the application is running quickly after the hardware has been reset.
- Simple Message Passing: Messages can be passed either from a system pool or a private pool, sent with either urgent status or a user-defined priority, and broadcast or task specific. For maximum flexibility, a receiving task can operate on either the same CPU as the sending task or on a different CPU within the same system.

For more information see the MQX web site at http://www.freescale.com/mqx.

#### **MQX RTOS—Customizable Component Set**

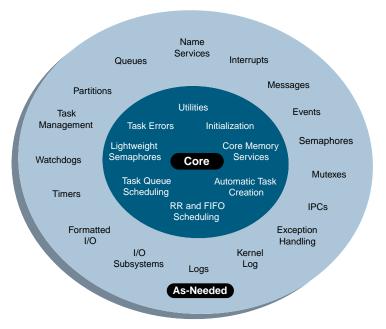


Figure 7. MQX Customizable Component Set

# 6.4 Additional Software Stacks Provided

- Math, DSP and Encryption Libraries
- Motor Control Libraries
- Touch Sensing Software Suite
- Complimentary Bootloaders (USB, Ethernet, RF, serial)
- · Complimentary Freescale Embedded GUI
- Complimentary Freescale MQX<sup>™</sup> RTOS , USB, TCP/IP stack and MFS filesystem
- Low Cost Nano TM SSL/Nano TM SSH for Freescale MQX TM RTOS
- Plus full ARM® ecosystem

# 7 Revision History

The following table provides a revision history for this document.

### **Table 9. Revision History**

Rev. No.	Date	Substantial Changes
4	6/2010	Initial public revision

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